

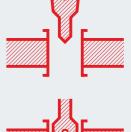
CONNECTING THE FUTURE

THE EloPin[®] BY INOVAN

Actuators, sensors, ECUs – the digital future needs reliable contacts. Our comprehensive portfolio of press-fit contacts offers you a precise, solderless contact technology that's gentle to PCBs.

FOR THE DEMANDS OF THE FUTURE

The EloPin®, and similar press-fit contacts developed by INOVAN, have for years been delivering great results when it comes to solderless electrical connection that's gentle to PCBs. Their cost-effectiveness and low error rate, combined with growing market demand, make these press-fit technologies a highly future-oriented contact solution – ideal for the demanding automotive applications of the future!





THE EloPin[®] BY INOVAN A RELIABLE CONNECTION BY YOUR RELIABLE PARTNER

Thanks to their attractive combination of high elasticity and maximum mechanical stability (low press-in force, high pushout force), our press-fit contacts are used in a wide variety of industries. Extreme applications in the engine compartments of electric and self-driving cars at up to 175°C are a particular area of focus.



WIDE-RANGING APPLICATIONS



SOLDERLESS CONNECTION

A connection technology that's gentle to PCBs, without the need for a complex and error-prone soldering process.



VARIETY OF GEOMETRIES

In addition to the EloPin models, INOVAN also offers other press-fit contacts as well as customer-specific solutions.



EXTREMELY STABLE – HIGHLY ELASTIC

A unique combination of high elasticity and maximum mechanical stability.

MAXIMUM EFFICIENCY

Quick and simple to fit to printed circuit boards on both sides.

Can be used in a variety of industries, with a focus on auto-

motive applications of the future (such as electric vehicles).

ENVIRONMENTS FROM -40 TO 175°C

Extremely robust and certified for high-temperature applications up to 175°C.

More information about all EloPin[®] models and INOVAN press-fit contacts:

www.inovan.de/pressfit

- 🖂 kontakttechnologie@inovan.de
- Speak to an advisor: +49 (7231) 493-634 or -241

Contact us!





PRESSFIT

- secure solderless connection up to 175°C
- INOVAN pressfit contact 0.60mm, 0.64mm und 0.80mm
- EloPin pressfit 0.6mm, 0.8mm
- base material CuSn6 or CuNiSi
- surface Ni/Sn
- extensive test phase concluded
- sealed in the injection tool
- application for example in control units, sensors, actuators

TECHNICAL SPECIFICATIONS

Name	Inovan Pressfit	Inovan Pressfit	Inovan Pressfit	EloPin 06-10	EloPin 08-145	EloPin 08-16
material thickness	0.60mm	0.64mm	0.80mm	0.6mm	0.8mm	0.8mm
circuit board bore (tin-plated)	1mm +0.09/-0.06	1mm +0.09/-0.06	1.60mm +0.09/-0.06	1,00mm +0,09/-0,01	1,45mm +0,09/-0,01	1,60mm +0,09/-0,01
standard check	IEC 60352-5					
surface	electroplated Sn mat over Ni					
material	CuSn6, CuNiSi			CuSn6; different CuNiSi alloys (only approved producers)		
temperature range	CuSn6: -40°C to + 125°C			CuSn6: -40°C to + 95°C		
	CuNiSi: -40°C to + 175°C			CuNiSi: -40°C to + 150°C		
press-in force, max.	130N			100N	160N	160N
press-out force (new state), min.	40N			30N	40N	50N
contact resistance*	≤ I mOhm					
current carrying capacity**	14 – 18A			ca. 8A	ca. 25A	ca. 25A

* according to IEC 60352-5

** dependent on the application

